



Is Now Part of



**ON Semiconductor®**

To learn more about ON Semiconductor, please visit our website at  
[www.onsemi.com](http://www.onsemi.com)

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.



# FSA7830

## 8-Channel Voltage MUX with Integrated Voltage Divider and OVP

### Features

- Voltage Supply, 2.7 to 5.5 V
- Input Voltage Range, 0 to 5.4 V
- Up to 8-Channel Inputs
- Integrated 1/3, 2/3 Voltage Divider
- Integrated Over-Voltage Protection and Assertion
- Total Introduced Offset <math>\lt; \pm 10 \text{ mV}</math>
- $I_{CC} < 100 \mu\text{A}</math>,  $I_{shut\text{down}} < 1 \mu\text{A}</math>$$
- 1.8 V I<sup>2</sup>C Interface, Addr<1:0> to Set Address for Multi Chip Solution
- 16-Ball, 0.4 mm Pitch, 1.56 mm x1.56 mm, WLCSP Package

### Applications

- Cell Phones
- Tablets

### Description

The FSA7830 is an 8-Channel, low-power Voltage MUX.

It integrates 8 analog switches for input voltage selection, and voltage dividers to provide 1/3, 2/3 fraction of selected voltage. With another 3 analog switches, FSA7830 provides feasibility to choose 1/3, 2/3 or 1 times of selected voltage.

FSA7830 also contains output buffer to enhance driving capability. It features over-voltage protection to ensure output less than 2 V, interrupt will be alerted at the same time.

FSA7830 supports 1.8 V I2C interface to communicate with processor, and 2 address pins to provide multi-chip solution.

### Ordering Information

Part Number	Top Mark	Operating Temperature Range	Package
FSA7830BUCX	GT	-40 to +85°C	16-Ball, 0.4 mm Pitch Wafer Level Chip Scale Package (WLCSP) Package (1.56 x 1.56 mm)

Typical Application

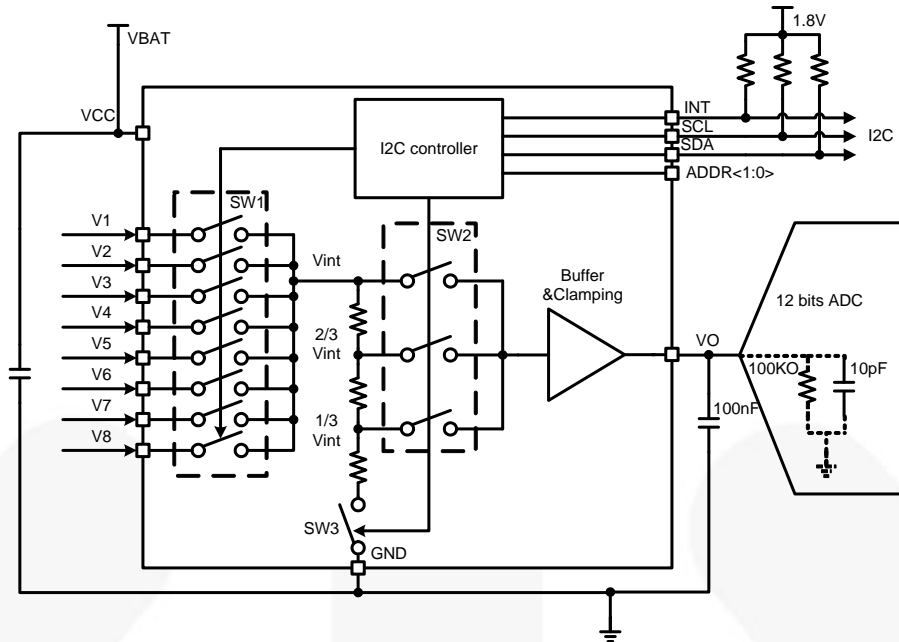


Figure 1. Application Diagram

## Pin Configuration

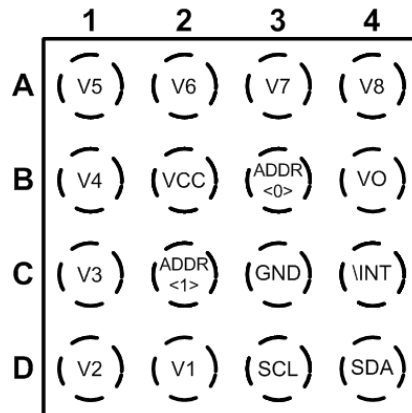


Figure 2. 16 Ball WLCSP Package(Top View)

## Pin Definitions

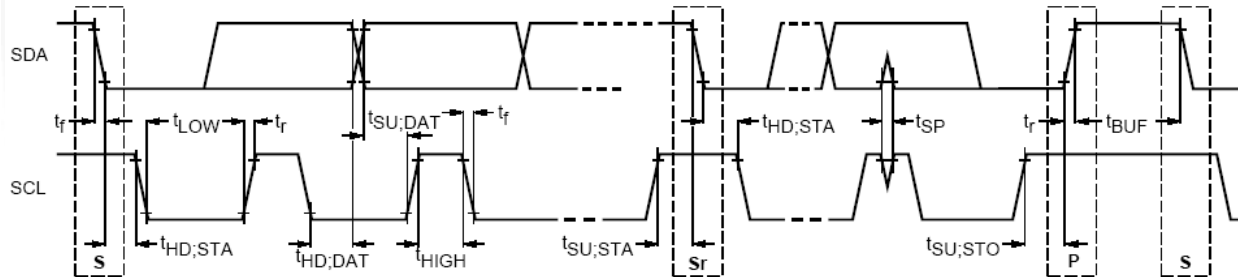
Pin#	Name	Description
A1	V5	Input Port 5
A2	V6	Input Port 6
A3	V7	Input Port 7
A4	V8	Input Port 8
B1	V4	Input Port 4
B2	VCC	Voltage Supply
B3	ADDR<0>	Address Pin, Bit 0
B4	VO	Output Voltage
C1	V3	Input Port 3
C2	ADDR<1>	Address Pin, Bit 1
C3	GND	Ground
C4	\INT	I2C Interrupt
D1	V2	Input Port 2
D2	V1	Input Port 1
D3	SCL	I2C Clock
D4	SDA	I2C Data

## I2C Specifications

Symbol	Parameter	Fast Mode		
		Min.	Max.	Unit
$f_{SCL}$	I2C_SCL Clock Frequency	0	400	kHz
$t_{HD,STA}$	Hold Time (Repeated) START Condition	0.6		$\mu$ s
$t_{LOW}$	LOW Period of I2C_SCL Clock	1.3		$\mu$ s
$t_{HIGH}$	HIGH Period of I2C_SCL Clock	0.6		$\mu$ s
$t_{SU,STA}$	Set-up Time for Repeated START Condition	0.6		$\mu$ s
$t_{HD,DAT}$	Data Hold Time	0	0.9	$\mu$ s
$t_{SU,DAT}$	Data Set-up Time <sup>(1)</sup>	100		ns
$t_r$	Rise Time of I2C_SDA and I2C_SCL Signals <sup>(1)</sup>	$20+0.1C_b$	300	ns
$t_f$	Fall Time of I2C_SDA and I2C_SCL Signals <sup>(1)</sup>	$20+0.1C_b$	300	ns
$t_{SU,STO}$	Set-up Time for STOP Condition	0.6		$\mu$ s
$t_{BUF}$	BUS-Free Time between STOP and START Conditions	1.3		$\mu$ s
$t_{SP}$	Pulse Width of Spikes that Must Be Suppressed by the Input Filter	0	50	ns

**Note:**

1. A fast-mode I2C-bus device can be used in a standard-mode I2C-bus system, but the requirement  $t_{SU,DAT} \geq 250$  ns must be met. This is automatically the case if the device does not stretch the LOW period of the I2C\_SCL signal. If such a device does stretch the LOW period of the I2C\_SCL signal, it must output the next data bit to the I2C\_SDA line  $t_{r,max} + t_{SU,DAT} = 1000 + 250 = 1250$  ns (according to the standard-mode I2C bus specification) before the I2C\_SCL line is released.



**Figure 1. Definition of Timing for Full-Speed Mode Devices on the I2C Bus**

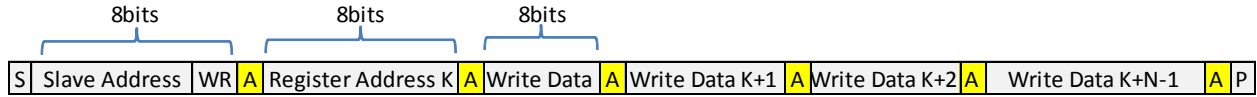
**Table 1. I<sup>2</sup>C™ Slave Address**

ADDR<1:0>	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
00	1	0	0	0	0	1	0	R/W
01	1	0	0	0	0	1	1	R/W
10	1	0	0	0	1	0	1	R/W
11	1	0	1	0	1	0	0	R/W

## I2C Interface

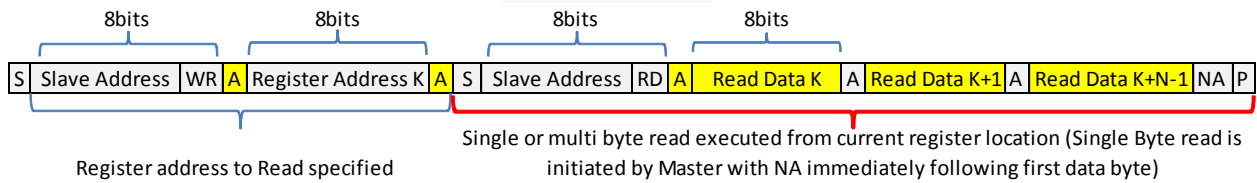
The FSA7830 includes a full I2C slave controller. The I2C slave fully complies with the I2C specification version 2.1 requirements. This block is designed for fast mode, 400 kHz, signals.

Examples of an I2C write and read sequence are shown in below Figure 3 and Figure 4 respectively.



**Note:** Single Byte read is initiated by Master with P immediately following first data byte

**Figure 3. I2C Write Example**



**Note:** If Register is not specified Master will begin read from current register. In this case only sequence showing in Red bracket is needed

From Master to Slave	<b>S</b> Start Condition	<b>NA</b> NOT Acknowledge (SDA High)	<b>RD</b> Read =1
From Slave to Master	<b>A</b> Acknowledge (SDA Low)	<b>WR</b> Write=0	<b>P</b> Stop Condition

**Figure 4. I2C Read Example**

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
$V_{CC}$	Supply Voltage	-0.5	6	V
$V_{1\sim 8}$	Input Voltage	-0.5	6	V
$I_{IK}$	DC Input Diode Current	-50		mA
$T_{STG}$	Storage Temperature	-65	+150	°C
MSL	Moisture Sensitivity Level (JEDEC J-STD-020A)		1	Level
ESD	Human Body Model, JEDEC: JESD22-A114	All Pins	2	kV
		I/O to GND	2	
		Power to GND	2	
	Charged Device Model, JEDEC: JESD22-C101	500	V	

## Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
$V_{CC}$	Supply Voltage	2.7	5.5	V
$V_{1\sim 8}$	Input Voltage	0	5.4	V
$V_{ADDR}$	Address Pin Voltage	0	$V_{CC}$	V
$V_{SCL, SDA, INT}$	I2C Bus Voltage Swing	0	1.8	V
$T_A$	Operating Temperature	-40	+85	°C

## DC Electrical Characteristics

All typical value are for  $V_{CC}=3.7\text{ V}$  at  $T_A=25^\circ\text{C}$ , with  $100\text{ K}\Omega$  and  $100\text{ nF}+10\text{ pF}$  loading at  $V_O$ , unless otherwise specified.

Symbol	Parameter	Condition	$V_{CC}$ (V)	$T_A=-40^\circ\text{C}$ to $+85^\circ\text{C}$			Unit
				Min.	Typ.	Max.	
$V_{IK}$	Clamp Diode Voltage	$I_{IN}=-18\text{ mA}$				-0.7	V
$V_{IH2C}$	High-Level Input Voltage		2.7 to 5.5	1.26			V
$V_{IL2C}$	Low-Level Input Voltage		2.7 to 5.5			0.54	V
$V_{HYSI2C}$	Hysteresis of Schmitt Trigger Inputs		2.7 to 5.5	0.09			V
$I_{I2C}$	Input Current of SDA, SCL and VINT	Input Voltage 0.26 V to 2 V	2.7 to 5.5	-10		10	$\mu\text{A}$
$I_{CCTI2C}$	$V_{CC}$ current when SDA or SCL is HIGH	Input Voltage 1.8 V	5.5			1	$\mu\text{A}$
$V_{IHADDR}$	High-Level Input Voltage		2.7 to 5.5	1.26			V
$V_{ILADDR}$	Low-Level Input Voltage		2.7 to 5.5			0.54	V
$V_{HYSADDR}$	Hysteresis of Schmitt Trigger Inputs		2.7 to 5.5	0.09			V
$V_{OLSDA}$	Low-Level Output Voltage of SDA Pin	4 mA Sink Current (Open-Drain)	2.7 to 5.5			0.36	V
$V_{OLINTN}$	Low-Level Output Voltage of VINT	4 mA Sink Current (Open-Drain)	2.7 to 5.5			0.36	V
$R_{ON1}$	Switch1 On Resistance		2.7 to 5.5		100	200	$\Omega$
$R_{ON2}$	Switch2 On Resistance <sup>(2)</sup>		2.7 to 5.5		100	200	$\Omega$
$R_{VD}$	Voltage Divider On Resistance <sup>(2)</sup>		2.7 to 5.5	1			$\text{M}\Omega$
$I_{CC}$	Quiescent Supply Current	All blocks in Enable Mode	2.7 to 5.5			100	$\mu\text{A}$
$I_{CCZ}$	Disable Mode Leakage Current		2.7 to 5.5	-1		3.9	$\mu\text{A}$
$I_{LEAK,ON}$	Leakage Current of each channel from V1-8 to GND in Enable Mode					2	$\mu\text{A}$
$I_{LEAK,OFF}$	Leakage Current of each channel from V1-8 to GND in Disable Mode					1	$\mu\text{A}$
$V_{OFFSET}$	Offset Voltage introduced by FSA7830, referring to $V_O$		2.7 to 5.5	-10		10	mV
$V_{OVP}$	Over-Voltage Protection Threshold (Low to High)	Register 06h set to '00'	2.7 to 5.5	1.87	2.00	2.15	V
$V_{OVP,HYS}$	Over-Voltage Assertion Hysteresis		2.7 to 5.5		50		mV
$V_{CLAMPING}$	Clamping Voltage on $V_O$ when OVP happens	Register 06h set to '00'	2.7 to 5.5	1.87	2.00	2.15	V
$V_{O,DYNAMIC}$	$V_O$ Dynamic Range	100 $\text{K}\Omega$ between $V_O$ to 0.9 V, output buffer has the ability to drive the target value with maximum 1% mismatch	2.7 to 5.5	0.5		2.1	V

**Note:**

- Guaranteed by Design.



## AC Electrical Characteristics

All typical value are for  $V_{CC}=4.2\text{ V}$  at  $T_A=25^\circ\text{C}$ , with  $100\text{ K}\Omega$  and  $100\text{ nF}+10\text{ pF}$  loading at VO, unless otherwise specified.

Symbol	Parameter	Condition	$V_{CC}$ (V)	$T_A=-40^\circ\text{C to }+85^\circ\text{C}$			Unit
				Min.	Typ.	Max.	
$C_i$	Input Capacitance on V1~8 <sup>(3)</sup>	F=1 MHz	2.7 to 5.5			50	pF
$t_{SETTLING}$	VO Settling Time after each Switching <sup>(3)</sup>	$R_S=50\ \Omega$ , $C_O=100\text{ nF}+10\text{ pF}$ , $R_O=100\text{ K}\Omega$ , VO reaches 99% of target value	2.7 to 5.5			200	$\mu\text{s}$
$t_{LOADRESPONSE}$	VO Buffer Load Response, Settling Time of Load Change <sup>(3)</sup>	Loading on VO switches from $100\text{ nF}$ to $C_O=100\text{ nF}+10\text{ pF}$ , $R_O=100\text{ K}$ . VO reaches 99% of target value	2.7 to 5.5			150	ns
PSRR	Power Supply Rejection Ratio of VO from $V_{CC}$	Power supply noise, F=217 Hz, $V_{pp}=50\text{ mV}$ , $C_O=100\text{ nF}+10\text{ pF}$ , $R_O=100\text{ K}\Omega$	2.7 to 5.5		70		dB
Xtalk	Cross Talk between V1~8	F=500 KHz, $V_{pp}=50\text{ mV}$ , $C_O=100\text{ nF}+10\text{ pF}$ , $R_O=100\text{ K}\Omega$	2.7 to 5.5		80		dB

**Note:**

- Guaranteed by characterization and not tested in production.

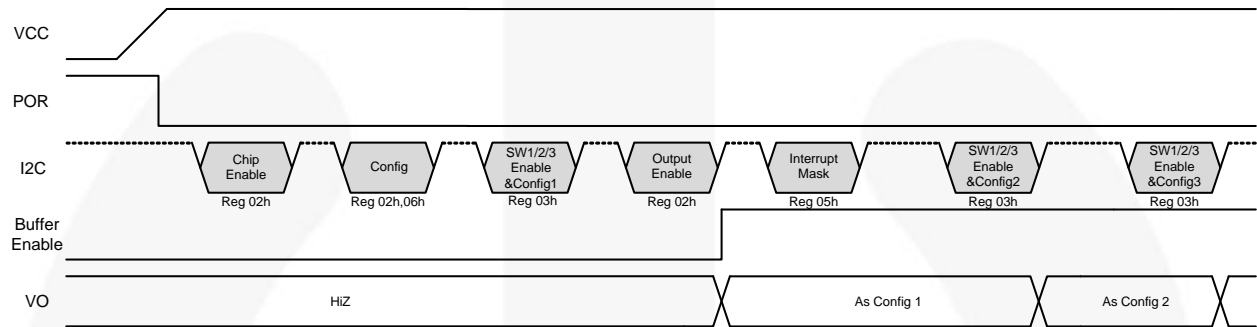
## Application Information

### Interrupt operation

The \INT pin is an active low, open drain output which indicates to the host processor that an interrupt has occurred in the FSA7830 which needs attention. The \INT pin is HIGH-Z by default after power-up or device reset.

The \INT pin stays HIGH-Z in preparation of future interrupts. When an interruptible event occurs, \INT is driven LOW and is HIGH-Z again when the processor clears the interrupt by reading the interrupt registers.

Subsequent to the initial power up or reset; if the processor writes a “1” to one of interrupt mask bits when the system is already powered up, the \INT pin stays HIGH-Z and ignores corresponding interrupt until the interrupt mask bit is cleared. If an event happens that would ordinarily cause an interrupt when the interrupt mask bit is set, the \INT pin goes LOW when the interrupt mask is cleared.



**Figure 5. Typical Application Sequence**

### Buffer & Clamping Enable Truth Table

To prevent non-ideal waveforms on VO node, enable of Output Buffer and Clamping circuitry depends on status of multi-internal register values.

**Table 2. Register Map**

Registers					Buffer & Clamping Enable
Chip Enable	SW1 Enable	SW2 Enable	SW3 Enable	Output Enable	
0	x	x	x	x	0
1	0	x	x	x	0
1	x	0	x	x	0
1	1	1	x	0	0
1	1	1	x	1	1

## Register Definitions

**Table 3. Register Map**

Address	Register Name	Type	Rst Val	Description
0x01	Device ID	RO	08	Device Version and Revision
0x02	Control	RW	00	Device Control
0x03	SWCTL	RW	00	Switch Status Control
0x04	INT	RO	00	Interrupt
0x05	INT_MASK	RW	80	Interrupt Mask
0x06	OVP	RW	00	OVP Threshold

**Notes:**

- Do not use registers that are blank.
- Values read from undefined register bits are not defined and invalid. Do not write to undefined registers.

**Table 4. Register Device ID**

Address: 01h

Reset Value: 0x0000\_1000

Type: Read

Bits	Name	Size	Description
7:6	Vendor ID	2	Vendor ID
5:3	Version ID	3	Device Version ID
2:0	Revision ID	3	Revision History ID

**Table 5. Control**

Address: 02h

Reset Value: 0x0000\_0000

Type: Read/Write

Bits	Name	Size	Description
7	Chip Enable	1	FSA7830 Enable/Shutdown <b>0: Shutdown (all other registers, including bits&lt;6:0&gt; of this register, reset to default value)</b> 1: Enable
6	Output Enable	1	Output Buffer Enable <b>0: Disable, VO maintains HiZ</b> 1: Enable
<5:4>	OVP action	2	Actions after OVP <b>00: Clamp output voltage to 2 V (based on register 06h)</b> 01: Pull VO to 0V 10: No Action
<3:0>	Reserved	4	Do Not Use

**Table 6. SWCTL**

Address: 03h

Reset Value: 0x0000\_0000

Type: Read/Write

Bits	Name	Size	Description
7	SW1 Enable	1	Switch 1 Enable <b>0: All Switches Off</b> 1: One switch on, status based on <6:4>
<6:4>	SW1 Control	3	Switch 1 Control <b>000: V1 to Vint</b> 001: V2 to Vint 010: V3 to Vint 011: V4 to Vint 100: V5 to Vint 101: V6 to Vint 110: V7 to Vint 111: V8 to Vint
3	SW2 Enable	1	Switch 2 Enable <b>0: All Switches Off</b> 1: One switch on, status based on <2:1>
<2:1>	SW2 Control	2	Switch 2 Control <b>00: VO to Vint</b> 01: VO to 1/3Vint 10: VO to 2/3Vint 11: Reserved
0	SW3 Control	1	Switch 3 Control <b>0: SW3 OFF</b> 1: SW3 ON

**Table 7. INT**

Address: 04h

Reset Value: 0x0000\_0000

Type: Read/Clear

Bits	Name	Size	Description
7	OVP	1	<b>0: OVP event has not occurred</b> 1: OVP event has occurred
<6:0>	Reserved	7	Do Not Use

**Table 8. INT\_MASK**

Address: 05h

Reset Value: 0x1000\_0000

Type: Read/Write

Bits	Name	Size	Description
7	OVP	1	0: Do not mask OVP interrupt <b>1: Mask OVP interrupt</b>
<6:0>	Reserved	7	Do Not Use

**Table 9. OVP**

Address: 06h

Reset Value: 0x0000\_0000

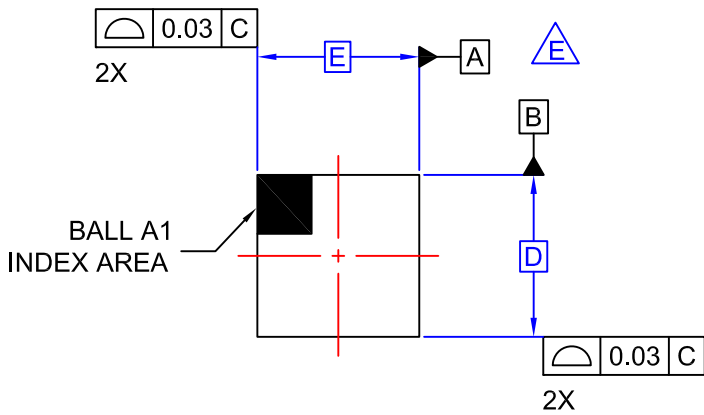
Type: Read/Write

Bits	Name	Size	Description
<7:3>	Reserved	5	Do Not Use
<2:0>	OVP Threshold	3	Over-voltage protection threshold <b>000: Default</b> 001: +50 mV 010: +100 mV 011: -250 mV 100: -50 mV 101: -100 mV 110: -150 mV 111: -200 mV

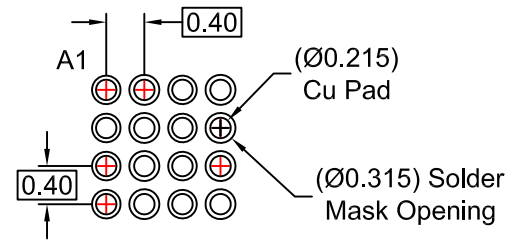
The table below pertains to the WLCSP package information on the following page.

**Physical Dimensions**

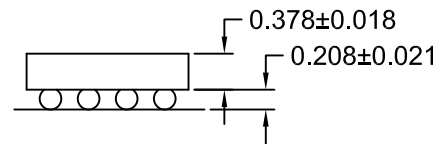
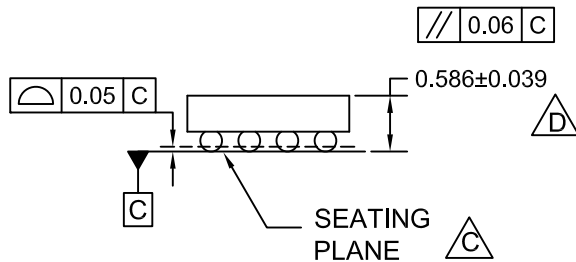
Product	D	E	X	Y
FSA7830BUCX	1.56 mm	1.56 mm	0.18 mm	0.18 mm



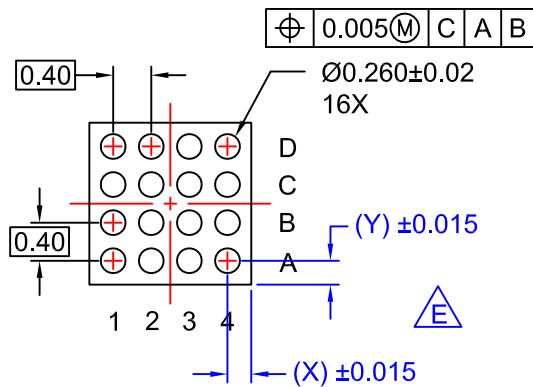
TOP VIEW



RECOMMENDED LAND PATTERN  
(NSMD PAD TYPE)



SIDE VIEWS



BOTTOM VIEW

NOTES

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- D. PACKAGE NOMINAL HEIGHT IS  $586 \pm 39$  MICRONS (547-625 MICRONS).
- E. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
- F. DRAWING FILNAME: MKT-UC016AF revA

ON Semiconductor



ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## PUBLICATION ORDERING INFORMATION

### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor  
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA  
**Phone:** 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
**Fax:** 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
**Email:** [orderlit@onsemi.com](mailto:orderlit@onsemi.com)

**N. American Technical Support:** 800-282-9855 Toll Free  
USA/Canada  
**Europe, Middle East and Africa Technical Support:**  
Phone: 421 33 790 2910  
**Japan Customer Focus Center**  
Phone: 81-3-5817-1050

**ON Semiconductor Website:** [www.onsemi.com](http://www.onsemi.com)  
**Order Literature:** <http://www.onsemi.com/orderlit>  
For additional information, please contact your local  
Sales Representative